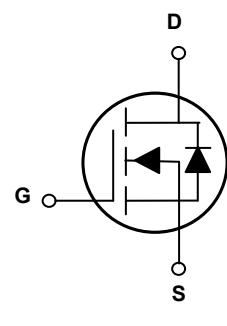
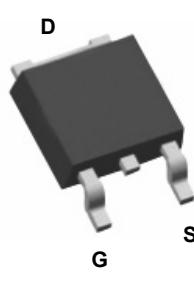


## Main Product Characteristics

$V_{DS}$	150V
$R_{DS(ON)}$	65mΩ
$I_D$	20A



## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSGD1520 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	150	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	20	A
Drain Current-Continuous ( $T_c=100^\circ\text{C}$ )		14	
Drain Current-Pulsed	$I_{DM}$	80	A
Single Pulse Avalanche Energy <sup>5</sup>	$E_{AS}$	65	mJ
Maximum Power Dissipation	$P_D$	68	W
Derating Factor		0.45	W/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Case <sup>2</sup>	$R_{\theta JC}$	2.2	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 To +175	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +175	$^\circ\text{C}$



# GSGD1520

## 150V N-Channel MOSFET

### Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	150	-	-	V
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=150\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Source Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics<sup>3</sup></b>						
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}, \text{I}_D=250\mu\text{A}$	2.5	3.3	4.5	V
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=10\text{A}$	-	59	65	$\text{m}\Omega$
Forward Transconductance	$\text{g}_{\text{fs}}$	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=10\text{A}$	15	-	-	S
<b>Dynamic and Switching Characteristics<sup>4</sup></b>						
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=75\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1\text{MHz}$	-	600	-	pF
Output Capacitance	$\text{C}_{\text{oss}}$		-	74.7	-	
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$		-	10.8	-	
Turn-On Delay Time	$\text{t}_{\text{d(on)}}$	$\text{V}_{\text{DD}}=75\text{V}, \text{R}_{\text{L}}=7.5\Omega, \text{R}_{\text{G}}=3\Omega, \text{V}_{\text{GS}}=10\text{V}$	-	9.5	-	nS
Turn-On Rise Time	$\text{t}_r$		-	5.5	-	
Turn-Off Delay Time	$\text{t}_{\text{d(off)}}$		-	12.5	-	
Turn-Off Fall Time	$\text{t}_f$		-	3	-	
Total Gate Charge	$\text{Q}_g$	$\text{V}_{\text{DS}}=75\text{V}, \text{I}_D=10\text{A}, \text{V}_{\text{GS}}=10\text{V}$	-	12	-	nC
Gate-Source Charge	$\text{Q}_{\text{gs}}$		-	5.7	-	
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	2.7	-	
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Current <sup>2</sup>	$\text{I}_s$		-	-	20	A
Diode Forward Voltage <sup>3</sup>	$\text{V}_{\text{SD}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=10\text{A}$	-	-	1.2	V
Reverse Recovery Time	$\text{t}_{\text{rr}}$	$\text{I}_{\text{F}}=\text{I}_s, \text{di}/\text{dt}=100\text{A}/\mu\text{s}^3, \text{T}_J=25^\circ\text{C}$	-	29	-	nS
Reverse Recovery Charge	$\text{Q}_{\text{rr}}$		-	130	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design.
5. EAS condition:  $\text{T}_J=25^\circ\text{C}, \text{V}_{\text{DD}}=30\text{V}, \text{V}_G=10\text{V}, \text{L}=0.5\text{mH}, \text{R}_g=25\Omega$

### Typical Electrical and Thermal Characteristic Curves

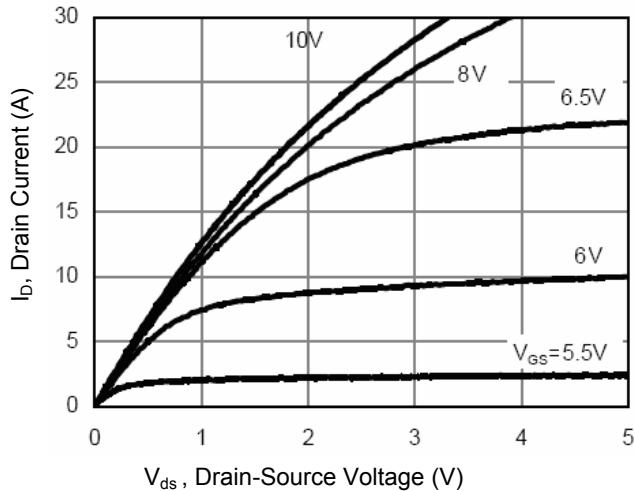


Figure 1. Output Characteristics

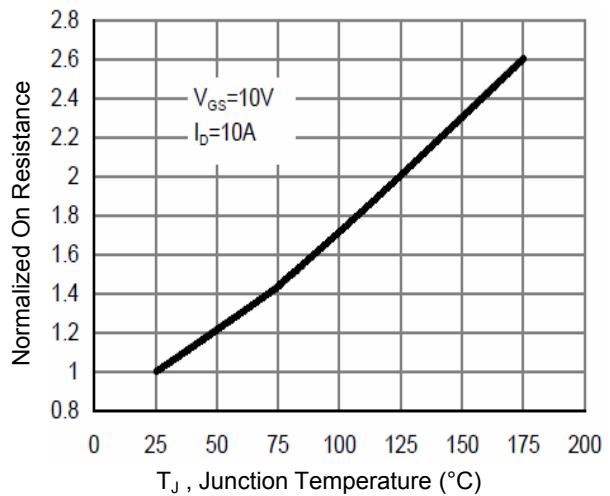


Figure 2.  $R_{DS(on)}$ -Junction Temperature

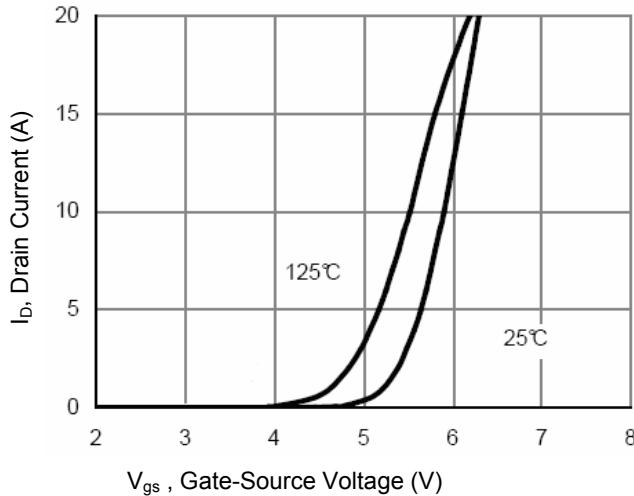


Figure 3. Transfer Characteristics

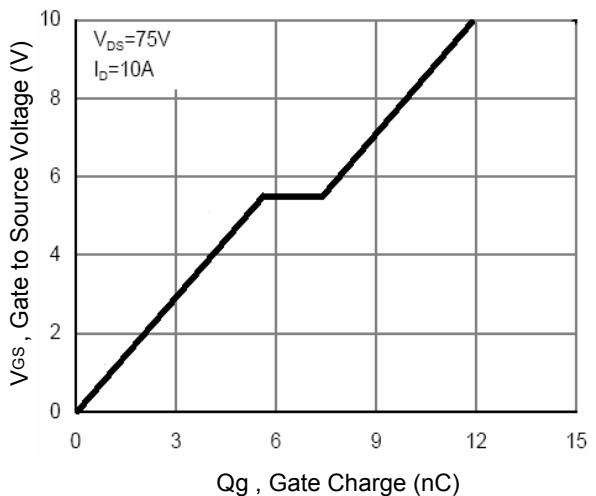


Figure 4. Gate Charge Waveform

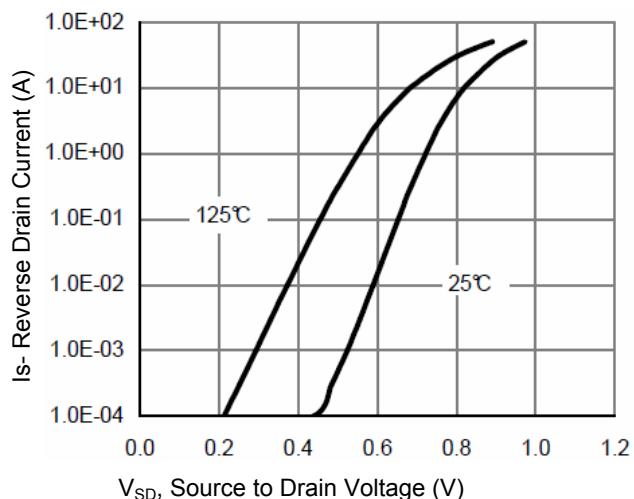


Figure 5. Source-Drain Diode Forward

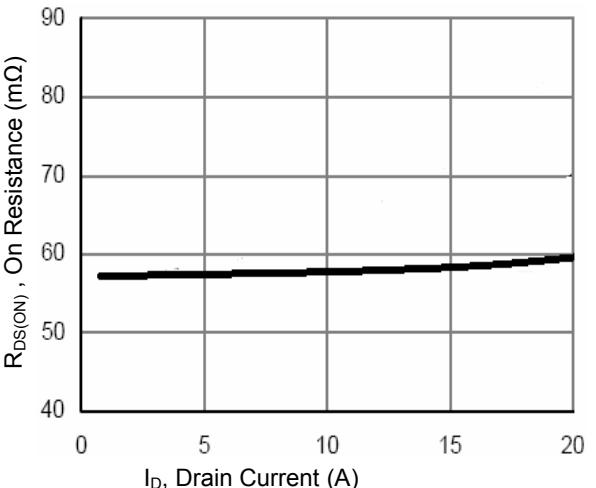


Figure 6.  $R_{ds(on)}$ -Drain Current

## Typical Electrical and Thermal Characteristic Curves

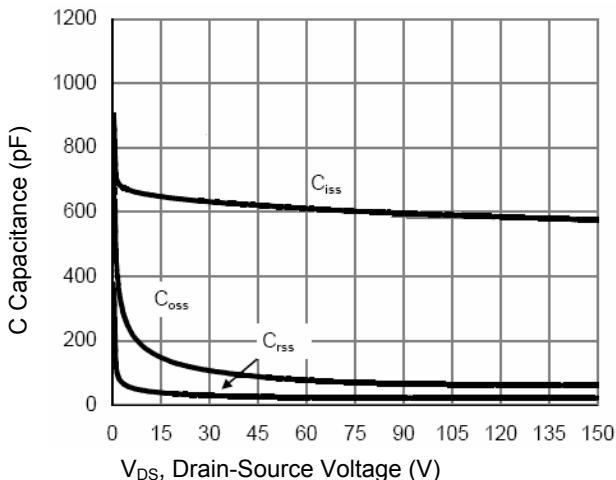


Figure 7. Capacitance vs.  $V_{DS}$

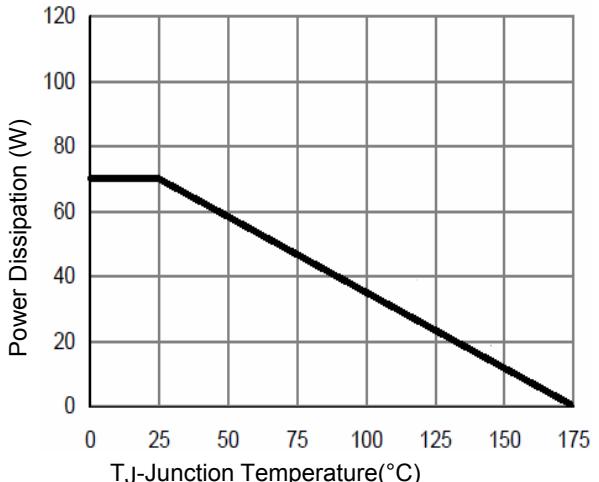


Figure 8. Power De-rating

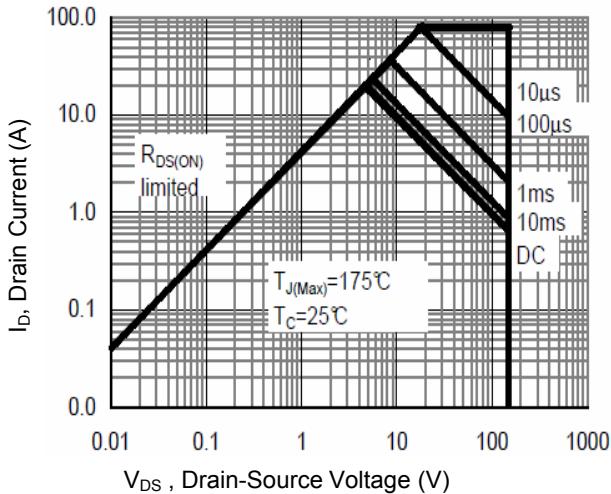


Figure 9. Safe Operation Area

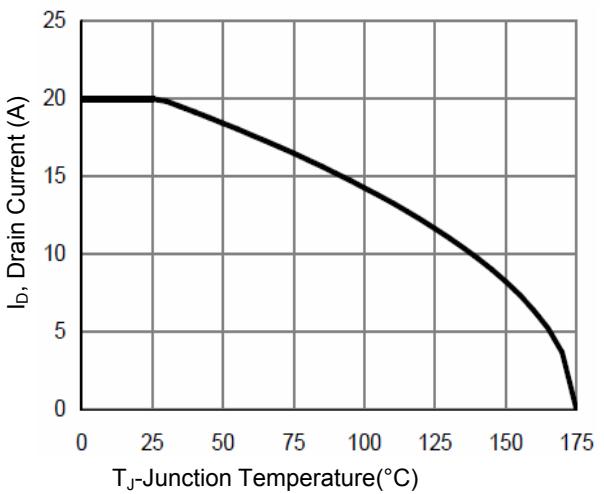


Figure 10. Current De-rating

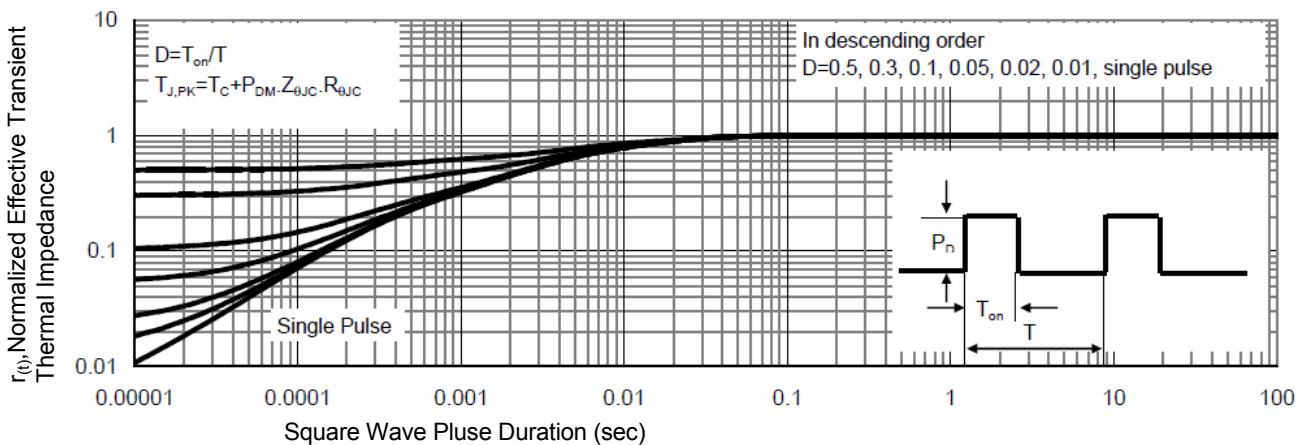


Figure 11. Normalized Maximum Transient Thermal Impedance

### Typical Electrical and Thermal Characteristic Curves

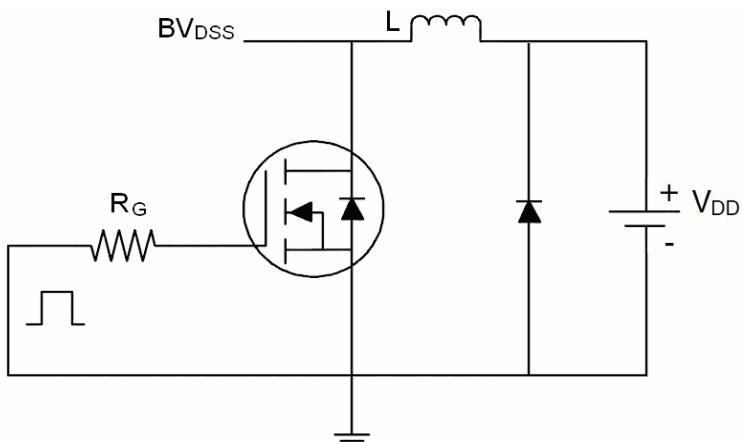


Figure 12.  $E_{AS}$  Test Circuit

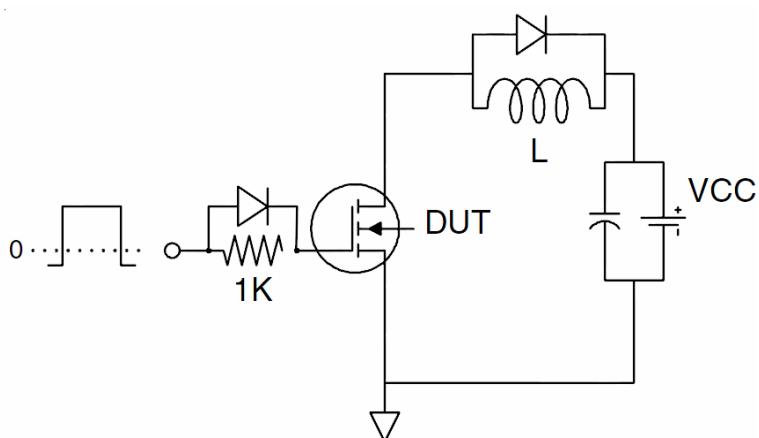


Figure 13. Gate Charge Test Circuit

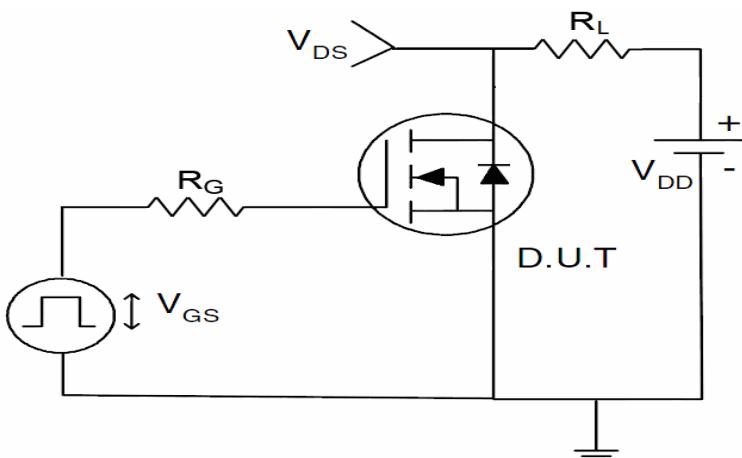
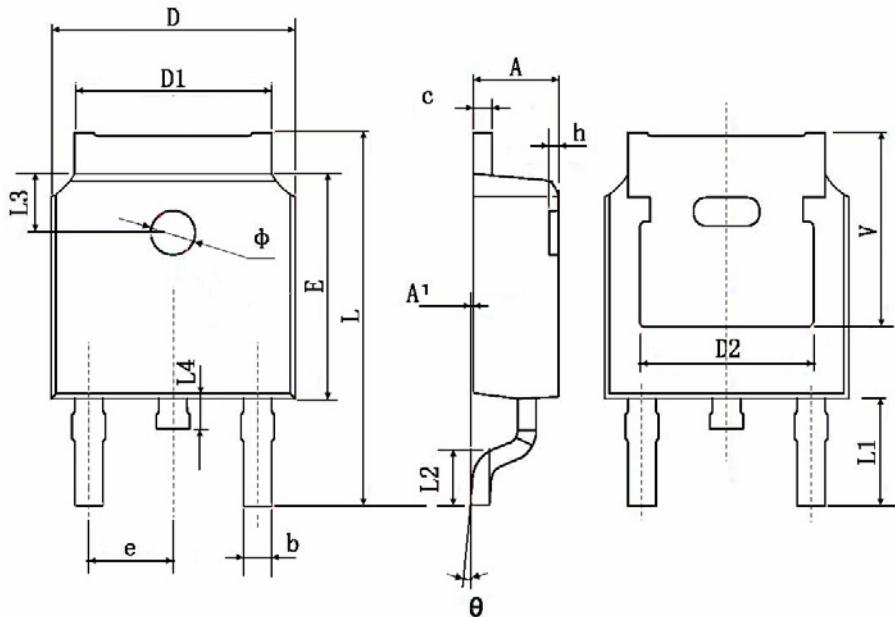


Figure 14. Switch Time Test Circuit

### Package Outline Dimensions (TO-252)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	